

## IN THE CLAIMS

1. (Currently Amended) A heater device, comprising:  
a heater defining a substantially horizontal planar upper heating surface; and  
a ceramic plate having a substantially horizontal planar lower surface conforming to and supported by said heating surface but not fastened thereto, the ceramic plate substantially entirely covering said upper heating surface, said ceramic plate including an upper supporting surface for supporting an object to be heated by heat conduction through said ceramic plate from said heater to such an object,

whereby said ceramic plate can be easily placed on and removed from said upper heating surface of said heater, wherein said ceramic plate is solid and devoid of openings for passing fluid therethrough, and wherein said heater consists of a ceramic heater and an electrode for radio frequency power is buried in said ceramic heater.

2. (Cancelled)

3. (Cancelled)

4. (Currently Amended) A heater device according to claim 1 ~~claim 3~~, wherein said ceramic plate has a thickness of no more than 2 mm.

5. (Currently Amended) A heater device ~~according to claim 1~~, comprising:  
a heater defining a substantially horizontal planar upper heating surface;  
and  
a ceramic plate having a substantially horizontal planar lower surface conforming to and supported by said heating surface but not fastened thereto, the ceramic plate substantially entirely covering said upper heating surface, said ceramic plate including an upper supporting surface for supporting an object to be heated by heat conduction through said ceramic plate from said heater to such an object,

wherein said ceramic plate can easily be placed on and removed from said upper heating surface of said heater,

wherein said ceramic plate is solid and devoid of openings for passing fluid therethrough, and

wherein an electrode for radio frequency power is buried in said ceramic plate.

6. (Original) A heater device according to claim 5, wherein said ceramic plate has a thickness of no more than 5 mm.

7. (Previously Presented) A heater device according to claim 1, wherein said ceramic plate is substantially made of ceramic material.

8. (Previously Presented) A heater device according to claim 1, wherein said ceramic plate further comprises an annular low wall surrounding said upper supporting surface.

9. (Currently Amended) A film forming device, comprising:  
a process vessel defining a process chamber;  
a heater defining a heating surface, said heater being placed in said process chamber;  
and  
a ceramic plate simply detachably placed on said heating surface of said heater without being fastened thereto so as to substantially entirely cover said heating surface and defining a supporting surface for supporting an object of a film forming process, wherein said ceramic plate is solid and devoid of openings for passing fluid therethrough-, and wherein said heater consists of a ceramic heater and an electrode for radio frequency power is buried in said ceramic heater.

10. (Previously Presented) A heater device according to claim 7, wherein said ceramic material consists essentially of aluminum nitride, magnesia, or alumina.

11. (Cancelled)

12. (Cancelled)

13. (Previously Presented) A film forming device according to claim 9, wherein said ceramic plate has a thickness of no more than 2 mm.

14. (Currently Amended) A film forming device ~~according to claim 9,~~  
comprising:  
a process vessel defining a process chamber;  
a heater defining a heating surface, said heater being placed in said process chamber;  
and  
a ceramic plate simply detachably placed on said heating surface of said heater  
without being fastened thereto to substantially entirely cover said heating surface, the ceramic  
plate defining a supporting surface for supporting an object of a film forming process,  
wherein said ceramic plate is solid and devoid of openings for passing fluid therethrough, and  
wherein an electrode for radio frequency power is buried in said ceramic plate.

15. (Previously Presented) A film forming device according to claim 9, wherein  
said ceramic plate has a thickness of no more than 5 mm.

16. (Previously Presented) A film forming device according to claim 9, wherein  
said ceramic plate is substantially made of ceramic material.

17. (Previously Presented) A film forming device according to claim 9, wherein  
said ceramic plate further comprises an annular low wall surrounding said supporting surface.

18. (Previously Presented) A film forming device according to claim ~~1~~ 16,  
wherein said ceramic material consists essentially of aluminum nitride, magnesia, or alumina.

19. (Previously Presented) A film forming device according to claim 9, wherein a  
pressure in the process vessel is controlled in a range of 0.5 torr to 10 torr.

20. (Currently Amended) A film forming device, comprising;  
a process vessel defining a process chamber;  
a heater defining a heating surface, said heater being placed in said process chamber;  
and  
a ceramic plate simply detachably placed on said heating surface of said heater  
without being fastened thereto so as to substantially entirely cover said heating surface and  
defining a supporting surface for supporting an object of a film forming process,

wherein said ceramic plate is substantially made of ceramic material-, and wherein said heater consists of a ceramic heater and an electrode for radio frequency power is buried in said ceramic heater.

21. (Cancelled)

22. (Currently Amended) A heater device, comprising:  
a heater defining a substantially horizontal planar upper heating surface; and  
a ceramic plate having a substantially horizontal planar lower surface conforming to and supported by said heating surface but not fastened thereto, the ceramic plate substantially entirely covering said upper heating surface, said ceramic plate including an upper supporting surface for supporting an object to be heated by heat conduction through said ceramic plate from said heater to such an object,

whereby said ceramic plate can be easily placed on and removed from said upper heating surface of said heater,

wherein said ceramic plate is substantially made of ceramic material-, and wherein said heater consists of a ceramic heater and an electrode for radio frequency power is buried in said ceramic heater.

23. (Previously Presented) The heater device of claim 22, wherein said ceramic plate is directly placed on said upper heating surface.

24. (Previously Presented) The heater device of claim 1, wherein said ceramic plate is substantially made of a ceramic material and has a thickness sufficient to be handled individually.

25. (Previously Presented) The heater device of claim 1, wherein the thickness ranges from 1 mm to 5 mm.

26. (Withdrawn) A method of using a heater device according to claim 1, comprising:  
providing the heater defining a substantially horizontal planar upper heating surface;  
and  
placing the ceramic plate on the upper heating surface;

placing a wafer on the ceramic plate;  
heating the wafer;  
removing the wafer from the ceramic plate; and  
removing the ceramic plate from the heater.